

MEG00-001C

Serial number 09/684,519

GP 2841



TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

From : George O. Saile (Reg. No. 19,572)
28 Davis Avenue
Poughkeepsie, NY 12603

Date: April 15, 2003

REF: APPLICANT : Jin-Yuan Lee
~~SERIAL NO.~~ : 09/684,519
~~ART UNIT~~ : 2841
~~FILING DATE~~ : 10/10/00
~~ATT'Y NO.~~ : MEG00-001C
~~EXAMINER~~ : Bui, Hung S.
TITLE : A THERMALLY COMPLIANT PCB
SUBSTRATE FOR THE APPLICATION
OF CHIP SCALE PACKAGES.

AMENDMENT AND RESPONSE TO OFFICE ACTION

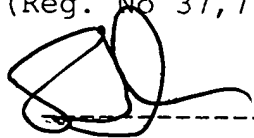
Sir:

In response to an office action mailed on 06/30/03, please consider the following amendments and remarks with respect to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal service as First Class mail in an envelop addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231, on June 30, 2003,

Stephen B. Ackerman (Reg. No 37,761)


Signature

6/30/03
Date

#14/Adt A
KZ
7/9/03

RECEIVED
JUN - 7 2003
TECHNOLOGY CENTER 2800